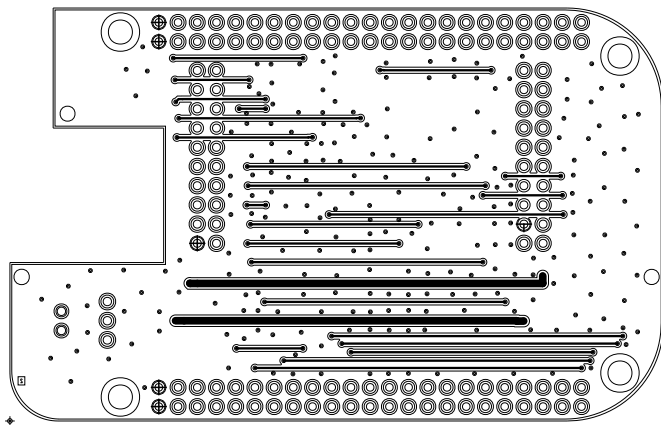
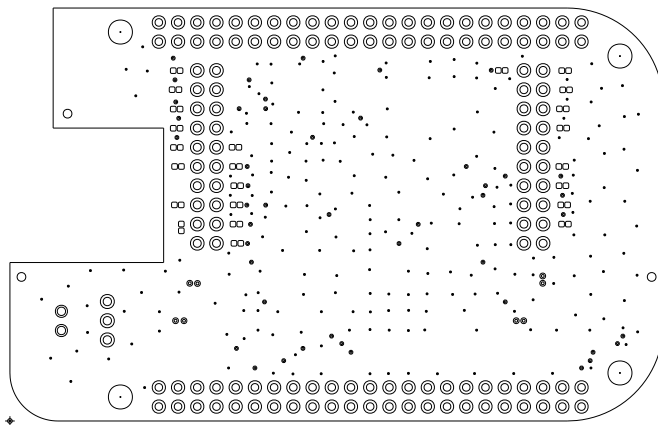


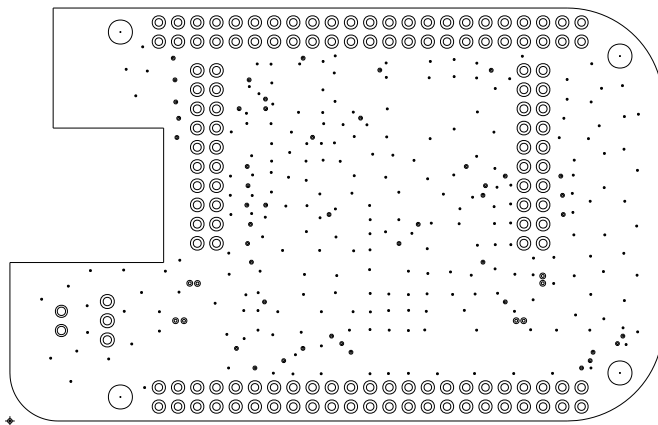
| | | | |
|--------------------------------|-----------------|------------------------------|--------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Top Layer | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 1 of 10 |



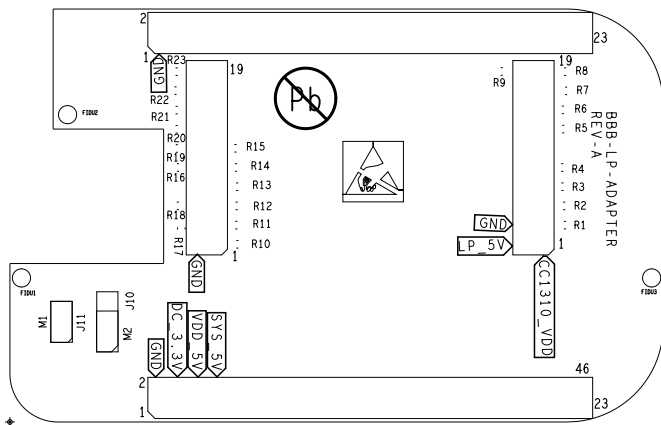
| | | | |
|--------------------------------|-----------------|---------------------------------|--------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Bottom Layer | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 4 of 10 |



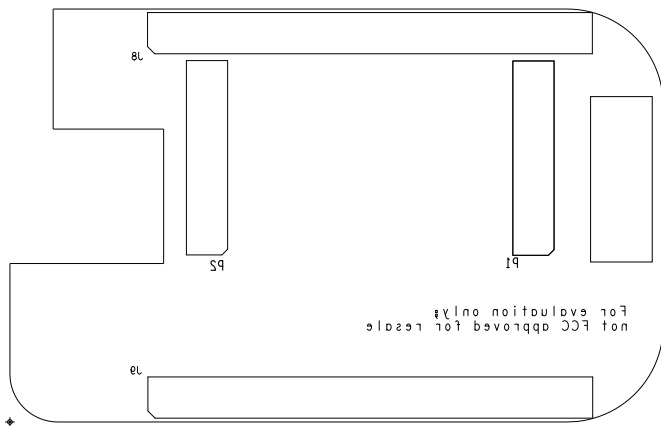
| | | | |
|--------------------------------|-----------------|-----------------------------------|--------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Soldermask-Top | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 5 of 10 |



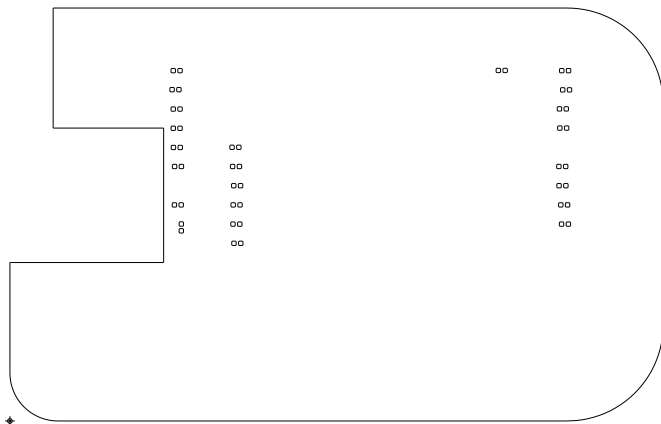
| | | | |
|--------------------------------|-----------------|--------------------------------------|--------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Soldermask-Bottom | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 6 of 10 |



| | | | |
|--------------------------------|-----------------|-----------------------------------|--------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Silkscreen-Top | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 7 of 10 |



| | | | |
|--------------------------------|-----------------|---|--------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: silkscreen-bottom | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 8 of 10 |



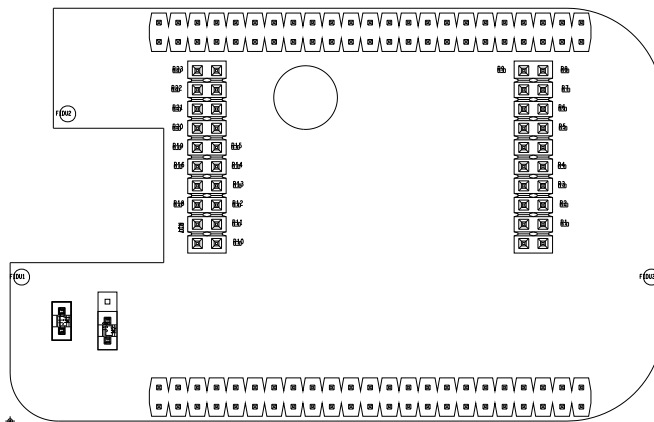
| | | | |
|--------------------------------|-----------------|-----------------------------------|--------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Pastemask- Top | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 9 of 10 |



| | | | |
|--------------------------------|-----------------|-------------------------------------|---------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Pastemask-Bottom | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 10 of 10 |

ASSEMBLY NOTES:

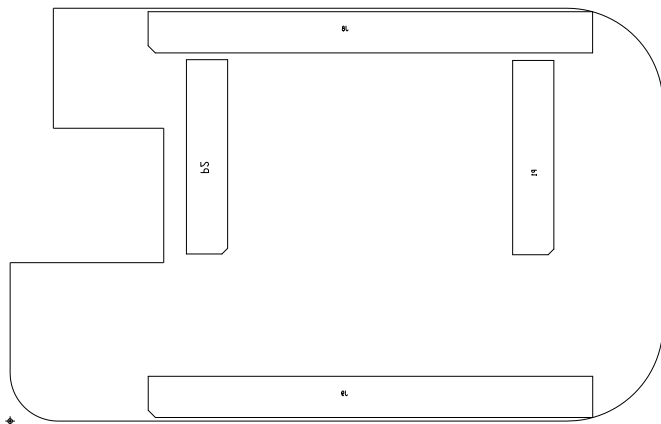
1. Connectors P1 and P2 should be mounted on Bottom side. The pins of the connectors should appear on the TOP side
2. Connectors J8 and J9 should be mounted on Bottom side. The long pins of the connectors should appear on the BOTTOM side



| | | | |
|--------------------------------|-----------------|---------------------------------|-------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Assembly-Top | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 1 of 2 |

ASSEMBLY NOTES:

1. Connectors P1 and P2 should be mounted on Bottom side.The pins of the connectors should appear on the TOP side
2. Connectors J8 and J9 should be mounted on Bottom side.The long pins of the connectors should appear on the BOTTOM side



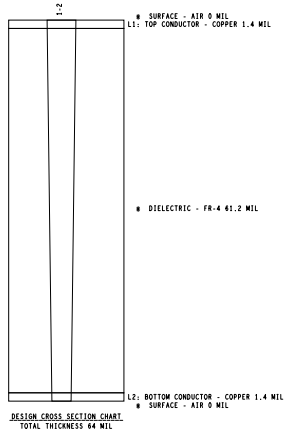
| | | | |
|--------------------------------|-----------------|------------------------------------|-------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Assembly-Bottom | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 2 of 2 |

FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. THE PWB SHALL BE FABRICATED TO IPC-6012 CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, ROHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B, ROHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. 94V-0 APPROVED AND MARKED ON THE FINISHED BOARD. UL RATING & UL GUIDE NUMBER SHOULD BE MARKED ON THE FINISHED BOARD.
5. OVERALL BOARD THICKNESS TO BE .064 +/- .005" AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
6. MAX. WARP & TWIST TO BE .0075 PER INCH.
7. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

PROCESS NOTES:

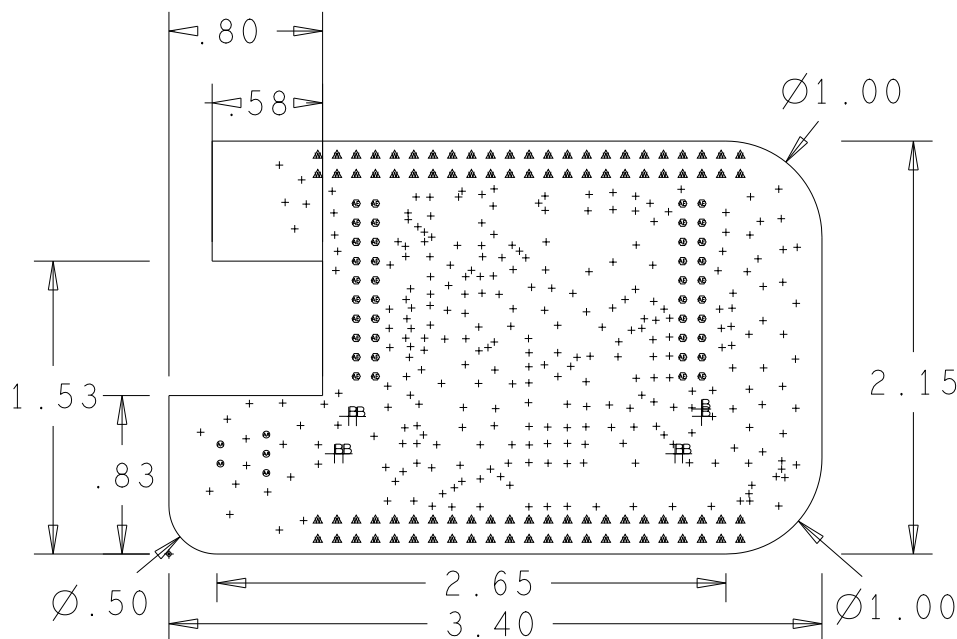
1. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC). SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS 'H', CURRENT REV. COLOR OF MASK TO BE RED.
2. PLATE ALL EXPOSED AREAS WITH ELECTROLESS NICKEL IMMERSION GOLD. NICKEL: 100 MICRO-INCHES MIN. GOLD: 2-8 MICROINCHES MIN.
3. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
4. APPLY NON-CONDUCTIVE LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
5. ALL VIAS ARE TENTED.



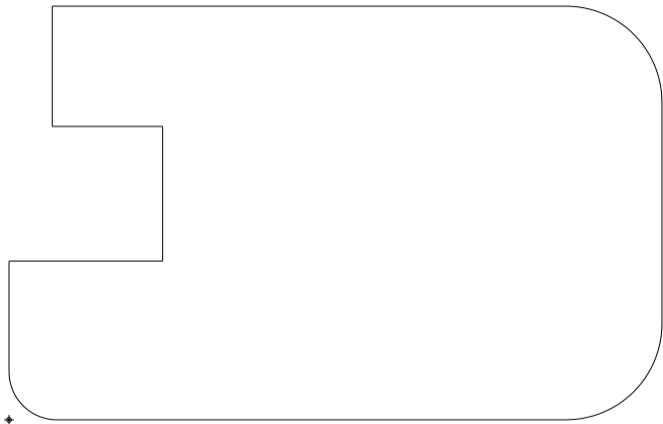
DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

| FIGURE | SIZE | TOLERANCE | PLATED | QTY |
|--------|-------|-------------|--------|-----|
| + | 10.0 | +3.0 / -3.0 | PLATED | 280 |
| ⊕ | 15.0 | +3.0 / -3.0 | PLATED | 8 |
| ▲ | 39.37 | +3.0 / -3.0 | PLATED | 92 |
| ⊙ | 41.34 | +3.0 / -3.0 | PLATED | 40 |
| ⊙ | 43.31 | +3.0 / -3.0 | PLATED | 5 |
| + | 125.0 | +3.0 / -3.0 | PLATED | 4 |



| | | | |
|--------------------------------|-----------------|---|-------------------------|
| CUSTOMER: Texas Instruments | | | |
| BOARD NAME: BBB-LP ADAPTER | | LAYER DESCRIPTION: Fabrication Drawing | |
| PROJECT NUMBER: WCS013 | BOARD REV: A | RELEASE DATE: 2016-09-29 | SHEET NUMBER: 1 of 1 |



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